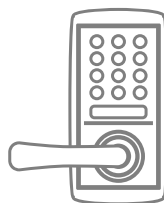


Wireless Earbuds

Solution Proposal by Toshiba

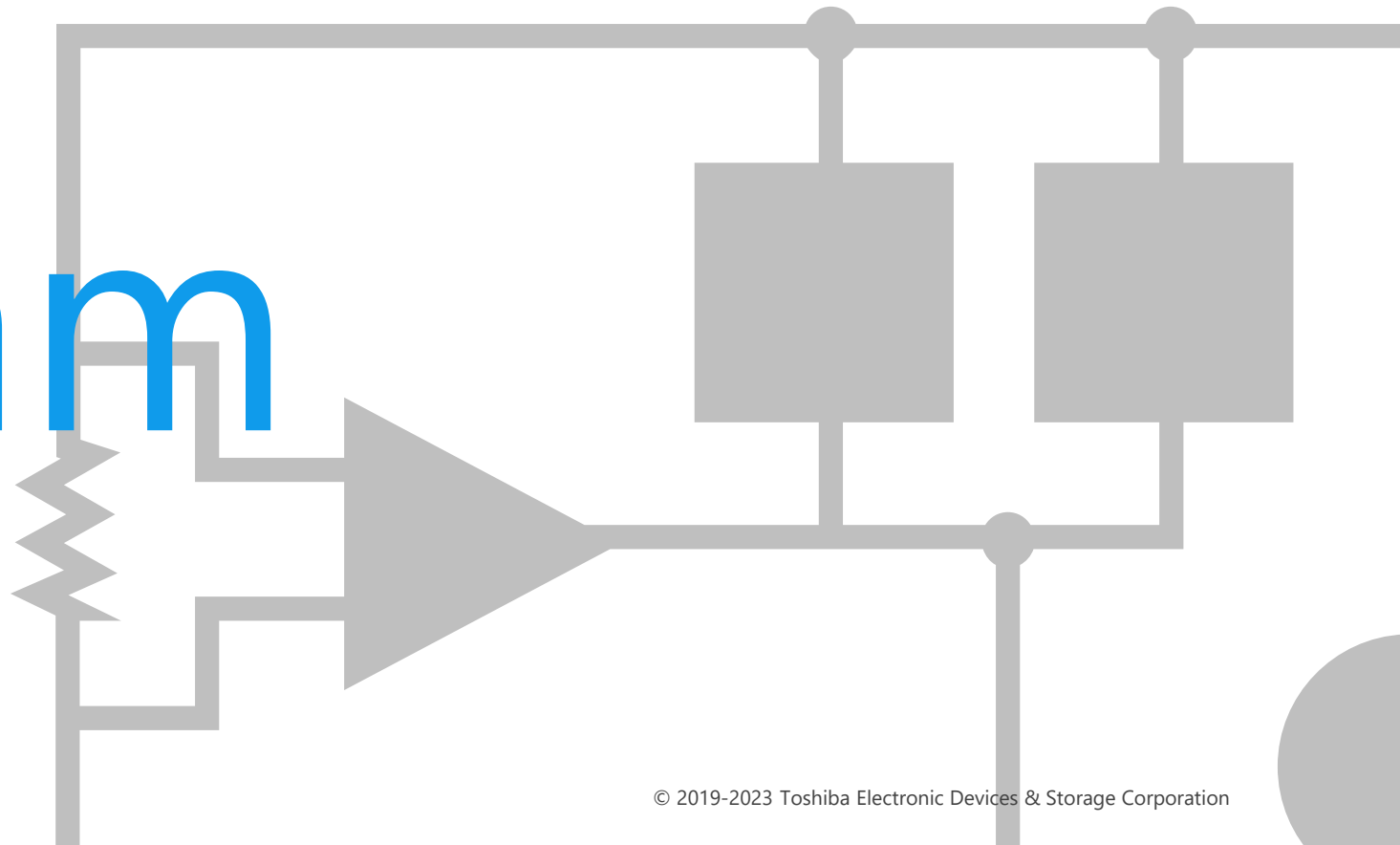




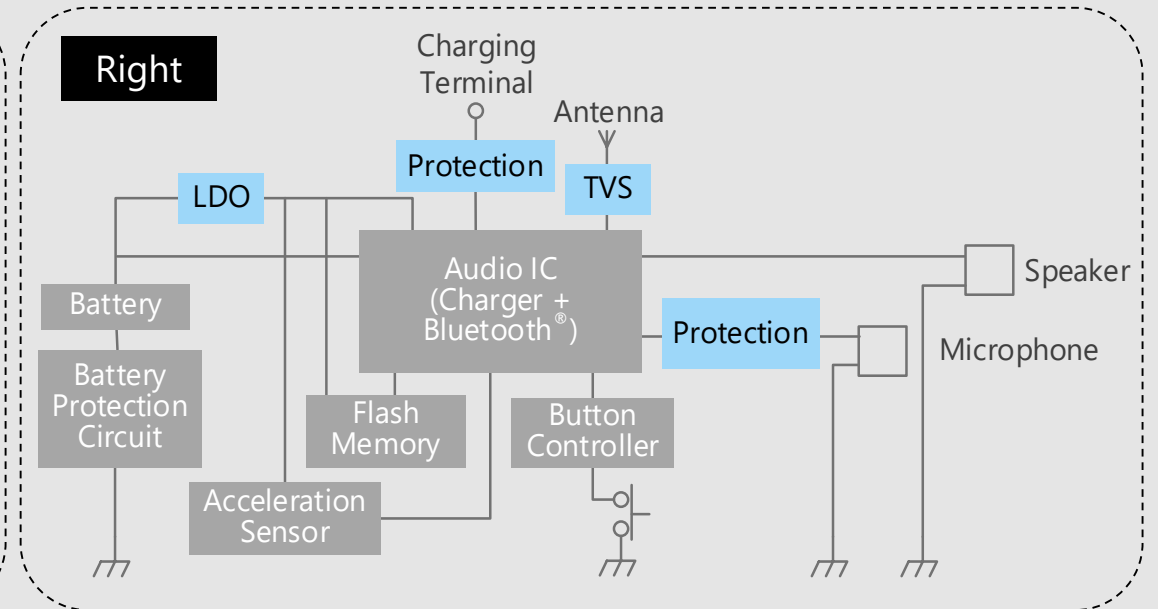
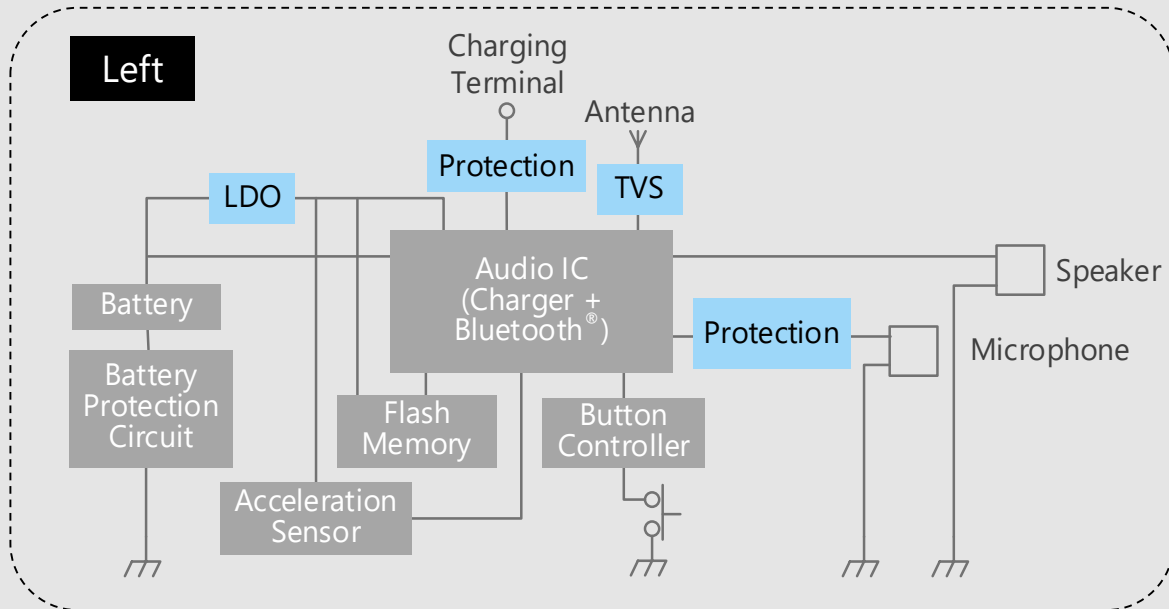
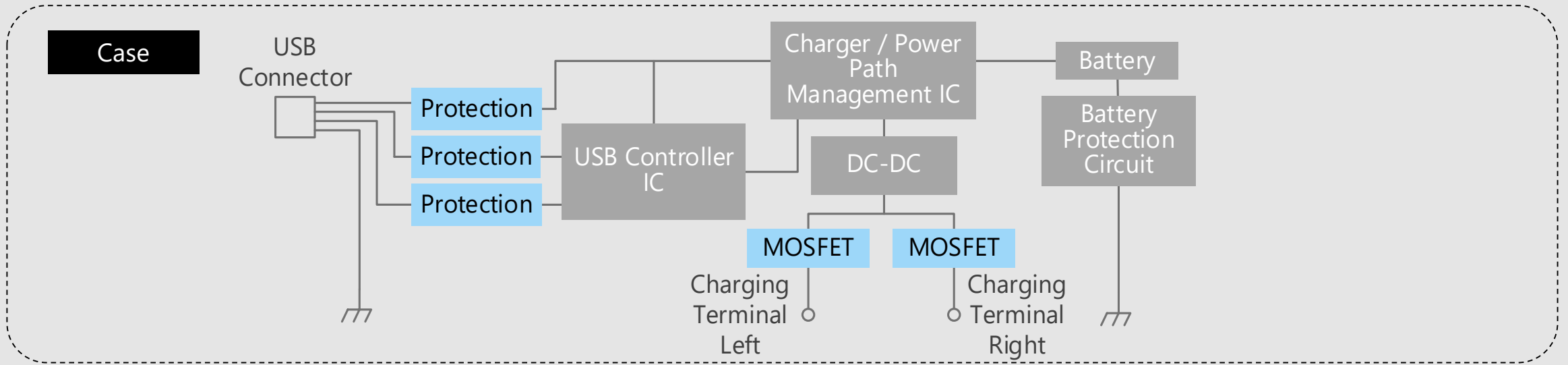
Toshiba Electronic Devices & Storage Corporation provides comprehensive device solutions to customers developing new products by applying its thorough understanding of the systems acquired through the analysis of basic product designs.



Block Diagram



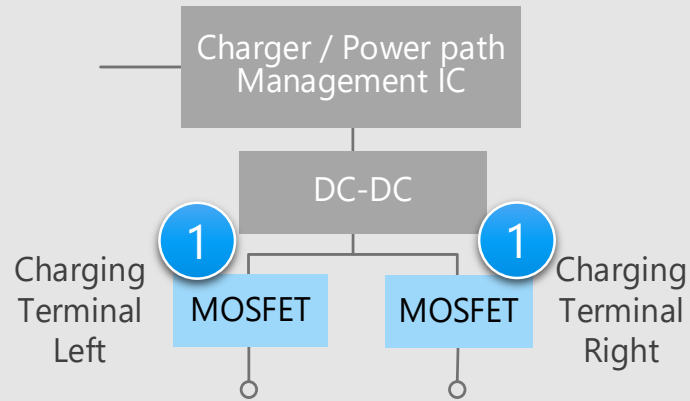
Wireless Earbuds Overall block diagram



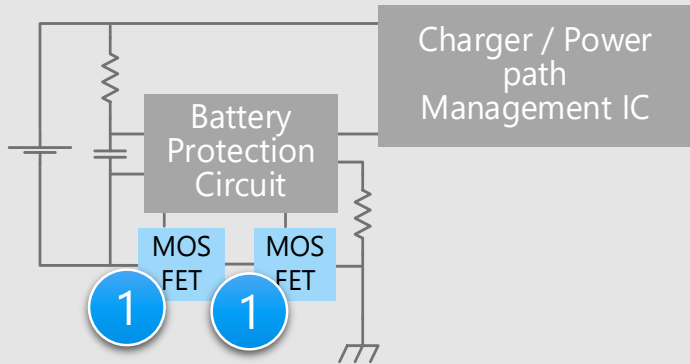
Wireless Earbuds Detail of earbuds case

Power supply lines

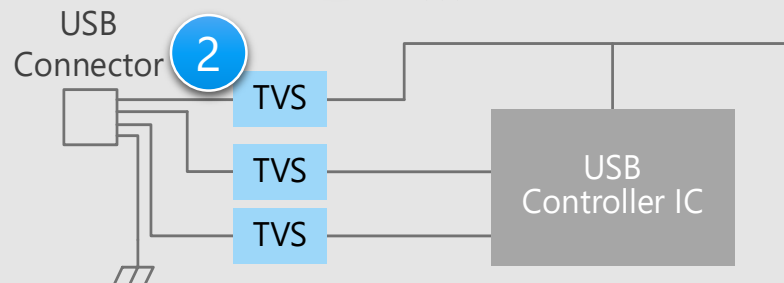
Load switch



Battery management



External connector



※ Click on the number in the circuit diagram to jump to the detailed description page

Criteria for device selection

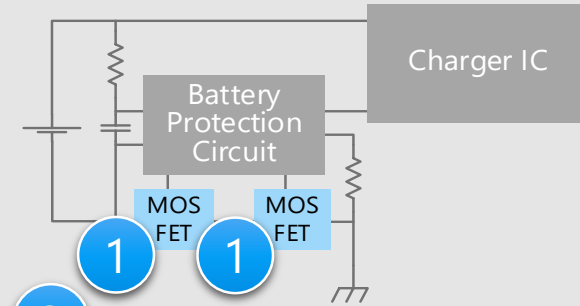
- MOSFET that can be driven at low voltage and prepared low on-resistance is suitable for load switch.
- Small package products contribute to the reduction of circuit board area.
- A compact TVS diode is suitable for ESD protection.

Proposals from Toshiba

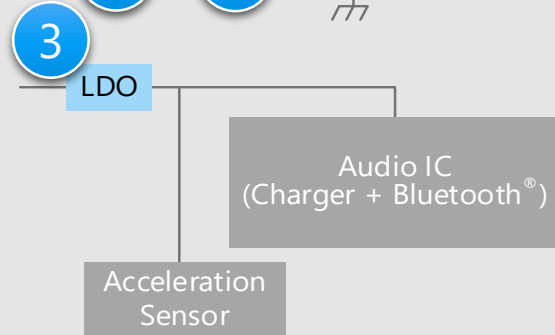
- **Realize a set with low power consumption by low on-resistance** 1
Small signal MOSFET
- **TVS diode that prepared compact size and rich lineup of capacitance** 2
TVS diode

Wireless Earbuds Detail of earbuds

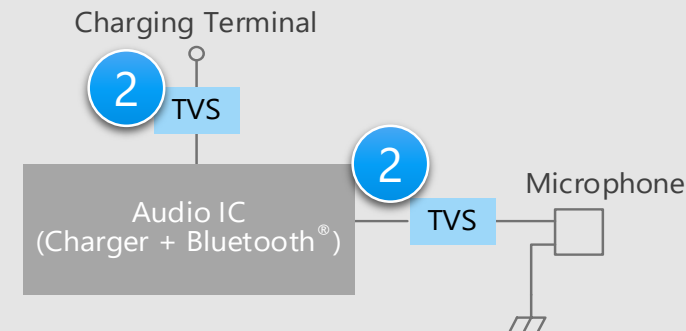
Battery management



Power supply circuit



Circuit protection



※ Click on the number in the circuit diagram to jump to the detailed description page

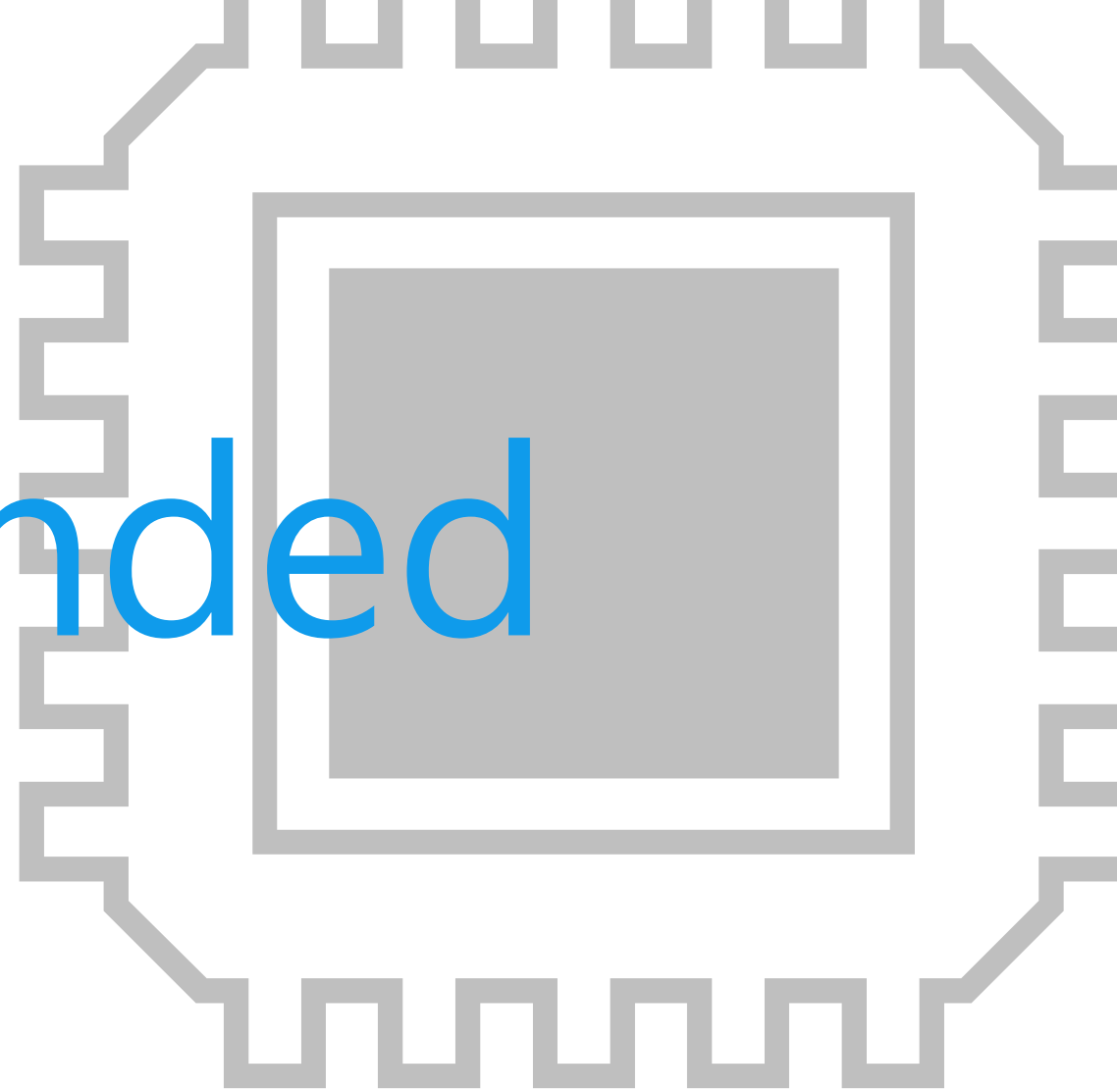
Criteria for device selection

- Small package products contribute to the reduction of circuit board area.
- MOSFET that can be driven at low voltage and prepared low on-resistance is suitable for battery management.
- PSRR (Power Supply Rejection Ratio) of LDO regulator is an important parameter for wireless system.
- A compact TVS diode is suitable for ESD protection.

Proposals from Toshiba

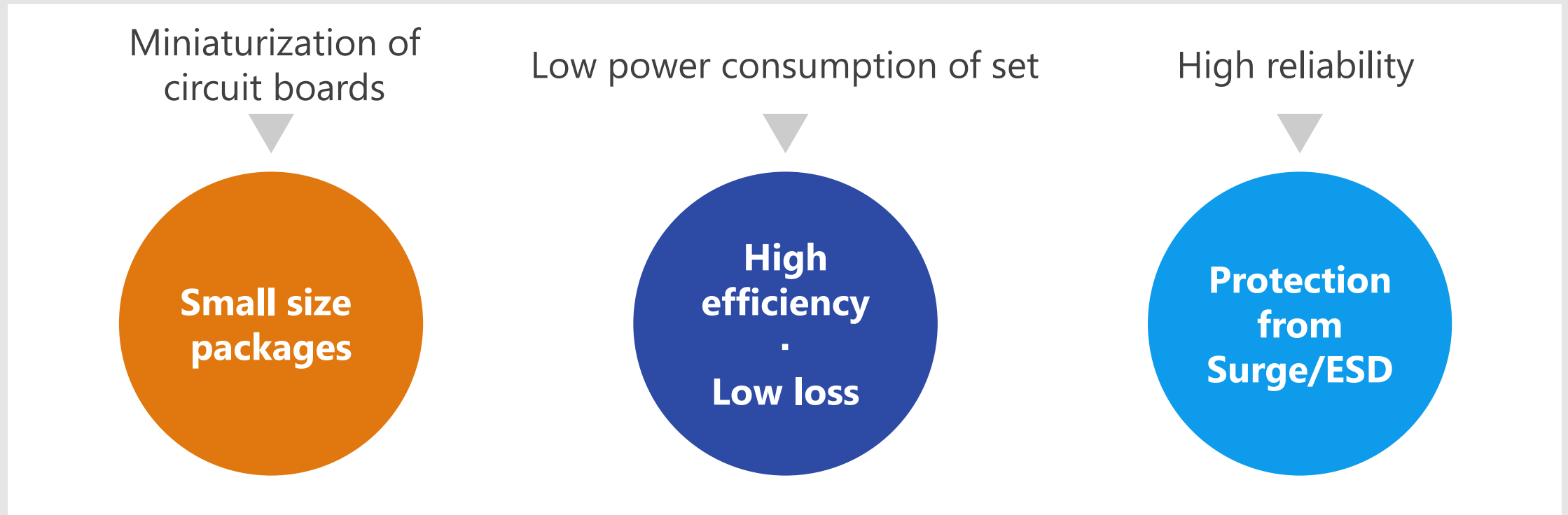
- **Realize a set with low power consumption by low voltage drive and low on-resistance**
Small signal MOSFET 1
- **TVS diode that prepared compact size and rich lineup of capacitance**
TVS diode 2
- **Provide small and low noise power supply**
Small surface mount LDO regulator 3

Recommended Devices



Device solutions to address customer needs

As described above, in the design of wireless earbuds, “**Miniaturization of circuit boards**”, “**Low power consumption of set**” and “**High reliability**” are important factors. Toshiba’s proposals are based on these three solution perspectives.



Device solutions to address customer needs

Small size packages

High efficiency
·
Low loss

Protection from Surge/ESD

① Small signal MOSFET	●	●	
② TVS diode	●		●
③ Small surface mount LDO regulator	●	●	

Value provided

Contribute to miniaturization and low power consumption of the set by low on-resistance and 2in1 package.

1 Low on-resistance

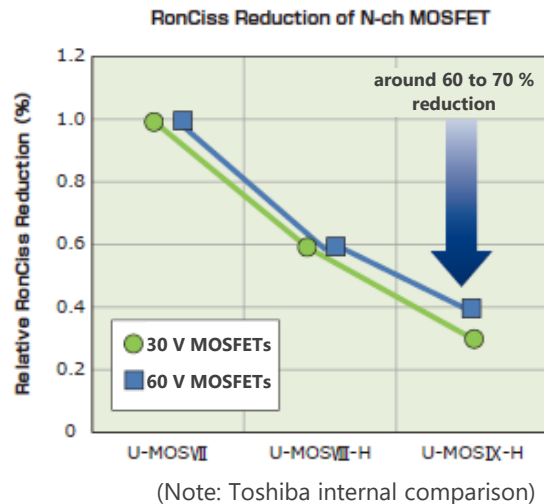
Heat dissipation and power consumption can be reduced by low drain-source on-resistance.

2 Low voltage drive

Power consumption of the set can be reduced by low voltage drive.

3 Small size package

Various packages, including ES6 packages (2in1), are available.



Lineup

Part number	SSM6N951L	SSM6N56FE	SSM6N61NU	SSM3K56ACT
Package	TCSP6A-172101	ES6	UDFN6	CST3
Polarity	N-ch x 2 (Drain Common)	N-ch x 2	N-ch x 2	N-ch
V_{DSS} / V_{SSS} [V]	12	20	20	20
I_D / I_S [A]	8	0.8	4	1.4
$R_{DS(ON)} / R_{SS(ON)}$ [mΩ] @ $V_{GS} = 2.5$ V	Typ.	5.5	230	31
	Max	10	300	45

[Return to Block Diagram TOP](#)

Value provided

Absorbs static electricity (ESD) from external terminals, prevents circuit malfunction and protects devices.

1 High ESD pulse absorption performance

Improved ESD absorption compared to our conventional products. (50 % reduction in operating resistance) For some products, both low operating resistance and low capacitance are realized and ensures high signal protection performance and signal quality.

2 Suppress ESD energy by low clamp voltage

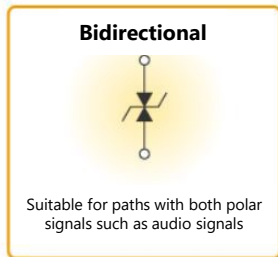
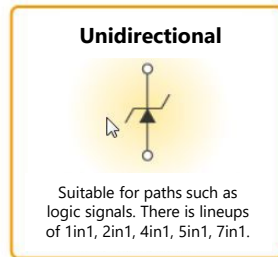
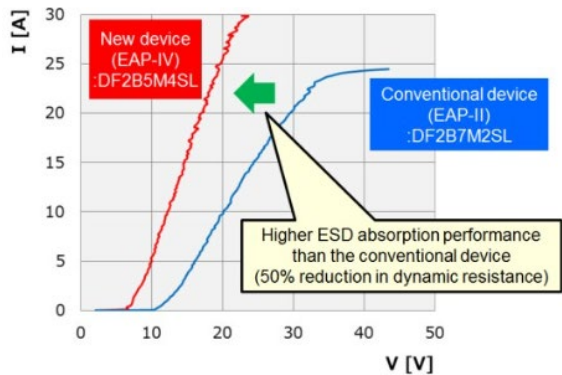
Protect the connected circuits/devices using Toshiba own technology.

3 Suitable for high density mounting


Another below table, a variety of compact packages are available.

ESD Pulse Absorption Performance

(NOTE: Toshiba internal comparison)



Lineup

Part number	DF2B6USL	DF2B6M4BSL	DF2B7BSL
Package	SL2 		
V_{ESD} [kV]	±10	±8	±30
V_{RWM} (Max) [V]	5.5	5.5	5.5
C_t (Typ.) [pF]	1.5	0.12	12
R_{DYN} (Typ.) [Ω]	0.25	1.05	0.2
Purpose	For signal lines	For signal lines	For signal / power supply lines

(NOTE) : This product is an ESD protection diode and cannot be used for purposes other than ESD protection

[Return to Block Diagram TOP](#)

3 Small surface mount LDO regulator

TCR5BM Series / TCR5RG Series / TCR3UG Series / TCR2EN Series

Small size packages

High efficiency
Low loss

Protection from Surge/ESD

Value provided

LDO regulator capable of low power and long life operation with low output voltage fluctuation by eliminating switching noise.

1 High PSRR

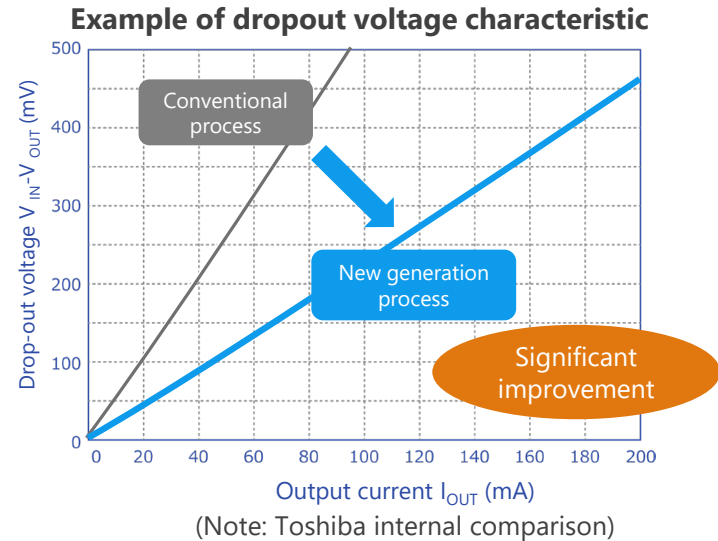
Our LDO regulator high PSRR (Power Supply Rejection Ratio) characteristic. Stable power supply is realized by removing switching noise generated in the circuit.



2 Low loss (low dropout)

Toshiba's LDO regulator has low loss characteristic and contributes to the suppression of heat generated in the circuit.

3 Suitable for high density mounting

Various packages are available.



Lineup				
Part number	TCR5BM Series	TCR5RG Series	TCR3UG Series	TCR2EN Series
Package	DFN5B 	WCSP4F 	SDFN4 	
I_{OUT} (Max) [A]	0.5	0.5	0.3	0.2
V_{DO} (Typ.) [mV]	100 @ $I_{OUT} = 500$ mA	150 @ $I_{OUT} = 500$ mA	140 @ $I_{OUT} = 300$ mA	160 @ $I_{OUT} = 150$ mA
PSRR (Typ.) [dB] @ $f = 1$ kHz	98	100	70	73
I_B (Typ.) [μ A]	19	7	0.34	35

[Return to Block Diagram TOP](#)

If you are interested in these products and have questions or comments about any of them, please do not hesitate to contact us below:

Contact address: <https://toshiba.semicon-storage.com/ap-en/contact.html>



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